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**Objective:** Verification of the existence of biotic agents in the final products of LANA S.COOP.

To whom it may Concern:

Following the request of LANA S.COOP with headquarters in Oñati (Spain) and Zdirec in Czech Republic the manufacturing process has been evaluated.

The wood used by LANA S.COOP comes from different European suppliers and they have the chain of custody (PEFC) certificate.

The wood comes dry and certify to Zdirec, also in Oñati the wood comes dry and with different humidity contents.

The wood used for the three-layer boards and beams is conveyed to the drying drums, where it is dried at 70 ° C for several hours, until the 12 % of humidity is reached. This process according to NIMF nº15 ensures that wood is rid of beetle's larvae.

When the  $12 \pm 3$  % of humidity is reached, it is transported to the screening machine to discard boards with imperfections or those that may have humidity higher than the indicated value

Afterwards, wooden planks are sawn to start the bonding and pressing stage. For three-layer boards IRU-PU and STD the pressing stage is performing at 125 °C for 6 minutes, while the beams are pressed at room temperature.

## Conclusions

Considering the above mentioned process it can be affirmed that IRU-PU and STD three-layer boards as well as HABE-20 beams are process in a way that ascertains that they are free of xylophages organism.

We will also like to emphasize that **NIMF n°15:2009** international standard, concerning the regulation of wood packaging material in international trade says; “The products that in their manufacturing process go through a drying stage or application of heat above 60 ° C are exempt from treatment”.

Therefore, RU-PU and STD three-layer boards as well as HABE-20 beams meet the requirements described in this standard.

Sincerely,



Blanca Ruiz de Gauna  
Jefe Laboratorio de Caracterización de  
Materiales de Construcción  
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